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Electronic Components Industry Association (ECIA)  
1111 Alderman Drive, Suite 400  
Alpharetta, GA 30005

Phone: (678) 393-9990  
Fax: (678) 393-9998

[rwillis@eciaonline.org](mailto:rwillis@eciaonline.org)

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# TABLE OF CONTENTS

<b>Capacitor Selection in Aviation Equipment .....</b>	<b>1</b>
<i>Shengxing Gu</i>	
<b>Aluminum Oxynitride Capacitors for Multilayer Devices with Higher Energy Density and Wide Temperature Properties .....</b>	<b>8</b>
<i>Kevin R. Bray, Richard L.C. Wu, Sandra Fries-Carr, Joseph Weimer</i>	
<b>Diamond-Like Carbon Capacitors for High Energy Density and High Temperature Operations .....</b>	<b>19</b>
<i>Richard L.C. Wu, Steve Finke, Joseph Veshinfsky, Mark Carter, Eric Smith, S. Lukich, Sandra Fries-Carr, Joseph Weimer, Marilyn Freeman</i>	
<b>Hybrid Capacitor Assembly Qualification .....</b>	<b>32</b>
<i>Nancy H. Clark, Wes E. Baca, Nancy J. Dhooge, David Evans, Tom Murphy</i>	
<b>Aluminium Electrolytic Capacitors' Performance in Very High Ripple Current and Temperature Applications .....</b>	<b>55</b>
<i>Leif Eliasson</i>	
<b>Power Delivery Challenges for Multi-Core Microprocessors .....</b>	<b>60</b>
<i>Larry E. Mosley</i>	
<b>Tantalum Capacitor Benchmark in Portable Audio Applications .....</b>	<b>69</b>
<i>R. Faltus, T. Zednicek, Ian Smith, J. Zajacek, J. Šikula</i>	
<b>Stable, Reliable, and Efficient Tantalum Capacitors .....</b>	<b>78</b>
<i>Yuri Freeman, Philip Lessner</i>	
<b>Decoupling Solutions .....</b>	<b>84</b>
<i>John Prymak, Erik Reed, Michael Randall, Peter Blais, Bill Long</i>	
<b>The Battle for Maximum Volumetric Efficiency - When Technologies Compete, Customers Win .....</b>	<b>98</b>
<i>Randy Hahn, Mike Randall, Jonathan Paulsen</i>	
<b>Film Capacitor Thermal Strategies Increase Power Density .....</b>	<b>111</b>
<i>Ralph M. Kerrigan, Bob Kropiewnicki</i>	
<b>Advanced Multilayer Capacitors Using High Energy Density Antiferroelectric Ceramics .....</b>	<b>117</b>
<i>Wesley Hackenberger, Seongtae Kwon, Edward Alberta</i>	
<b>Role of Wireless Modules, Using Embedded Passives, in The Expansion of Wireless Connectivity Solutions .....</b>	<b>129</b>
<i>Mehul Udani, Jerry Kolbe</i>	
<b>Why that 47 uF capacitor drops to 37 uF, 30 uF, or lower .....</b>	<b>139</b>
<i>John Prymak, Mike Randall, Peter Blais, Bill Long</i>	
<b>The Growing Importance of Inductance in Tantalum Capacitors .....</b>	<b>155</b>
<i>Erik Reed</i>	
<b>Printable Film Sensors .....</b>	<b>168</b>
<i>Walter Mathias, Kelly Lee</i>	
<b>Fabrication and Characterization of Nanolayer Capacitors .....</b>	<b>177</b>
<i>Robert Chow, Alan D. Ellis</i>	
<b>High Voltage Tantalum Polymer Capacitors .....</b>	<b>185</b>
<i>Jayson Young, Jake Qiu, Randy Hahn</i>	
<b>Electrochemical Reactions on Graphite Cathodes in High-Voltage Capacitors .....</b>	<b>196</b>
<i>Joachim Hossick-Schott, Mark E. Viste</i>	
<b>Process Development with Temperature Sensitive Components in Server Applications .....</b>	<b>204</b>
<i>L. G. Pymeto, W. T. Davis, Matthew Kelly, Marie Cole, Jim Wilcox, Paul Krystek, Curtis Grosskopf</i>	
<b>An Advanced Test Solution for Relay Stick, Miss and Functional Testing, Reflex 40 .....</b>	<b>220</b>
<i>S.J. Hobday</i>	
<b>Effect of Surge Current Testing on Reliability of Solid Tantalum Capacitors .....</b>	<b>233</b>
<i>Alexander Teverovsky</i>	
<b>Construction Improvement for Anti-sulfuration Chip Resistors .....</b>	<b>251</b>
<i>Chuangjun Huang, Haitao Du, Yongxiao Deng, Hongquan Wang</i>	
<b>Niobium Oxide and Tantalum Capacitors: Leakage Current, Restoring Voltage and Reliability .....</b>	<b>256</b>
<i>J. Sikula, V. Sedlakova, H. Navarova, J. Hlavka, M. Tacano, Z. Sita</i>	
<b>Shorting Failure In High Voltage Ceramic Capacitor With Floating Internal Electrode Structure .....</b>	<b>268</b>
<i>Yongwei Deng, Zhonghua Qi, Zhigang Tan, Congtu Xiao, He Cheng</i>	
<b>Complexities in The Deposition of Thin Film Resistors .....</b>	<b>276</b>
<i>Amit Das, Chris Grabbe, Robert Hufnagel</i>	

<b>Dielectric Improvement in NbO Capacitors</b> .....	290
<i>Z. Sita, M.Biler, T.Karnik, J. Sikula, V. Sedlakova</i>	
<b>New Polymer Dielectric For High Energy Density Film Capacitors</b> .....	300
<i>Paul Winsor IV, Edward Lobo, M. Zafar A. Munshi, Ayad Ibrahim</i>	
<b>Dispersed Spherical Silver Particles for Electronic Applications</b> .....	314
<i>Ionel Halaciuga, Dan V. Goia</i>	
<b>Process and Quality Improvement of Pastes and Inks Using MAZERUSTAR®</b> .....	322
<i>Gary Hemphill, Richard Stephenson</i>	
<b>Inkjet Printing of Silver Nanoparticles for Electronic Applications</b> .....	332
<i>Krishna Balantrapu, Meaghan McMurrin, Dan V. Goia</i>	
<b>Mass Production Techniques for Chip Resistors</b> .....	343
<i>Sam Tsai, Helen Yuan, Jelly Su, Jackie Hu</i>	
<b>The Growing Importance of Polyalkylene Carbonate Binders for the Passive Component Industry</b> .....	351
<i>Peter Ferraro, Sugianto Hanggodo</i>	
<b>Multilayer Polymer Aluminum Electrolytic Capacitors with Polypyrrole as Cathode Materials</b> .....	357
<i>Yining Kevin Zhang, Deyuan Pan, Sujing Chen, Junhong Lin, Yuanqiang Chen, Hui Yu, Zhangying Xiao, Xiong Chen, Gengyun Wu, Liang Guo, Youxiong Chen</i>	
<b>Use of Amorphous Oxides as High Temperature Dielectric Material in Wound Capacitors</b> .....	372
<i>Keith D. Jamison, Roger D. Wood, Byron G. Zollars, Martin E. Kordes</i>	
<b>Advances in Class-I COG MLCC and SMD Film Capacitors</b> .....	382
<i>Xilin Xu, Matti Niskala, Abhijit Gurav, Mark Laps, Kimmo Saarinen, Aziz Tajuddin, Davide Montanari, Francesco Bergamaschi, Evangelista Boni</i>	
<b>Author Index</b>	